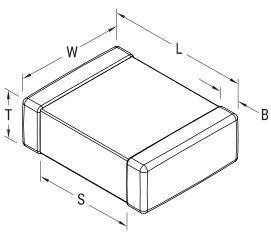




SMD Comm X8G HT150C Flex, Ceramic, 0.01 uF, 20%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1812, 2.3 mm



Click	here	for	the	3D	model	

1812
4.5mm +/-0.4mm
3.2mm +/-0.3mm
1mm +/-0.10mm
2.3mm MIN
0.7mm +/-0.35mm

Packaging Specifications		
Packaging	T&R, 330mm, Plastic Tape	
Packaging Quantity	4000	

General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	67 mg
Shelf Life	78 Weeks
MSL	1

Specifications		
Capacitance	0.01 uF	
Measurement Condition	1 kHz 1.0Vrms	
Tolerance	20%	
Voltage DC	250 VDC	
Dielectric Withstanding Voltage	625 VDC	
Temperature Range	-55/+150°C	
Temp. Coefficient	X8G	
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms	
Dissipation Factor	0.1% 1 kHz 1.0Vrms	
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours	
Insulation Resistance	100 GOhms	

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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